

## **PC-Mon-P18\* - Random telegraph noise and excess leakage current due to intrinsic defects in p-i-n diodes on GaN-on-Si substrate**

2. Physics and characterization

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**Abstract text:** GaN high electron mobility transistors (HEMTs) for power applications are typically built on Si substrates, resulting in dislocation densities of  $1\text{--}6 \times 10^9 \text{ cm}^{-2}$  within the GaN epitaxial layers [1,2]. The role of dislocations in the electrical properties and reliability of GaN HEMTs is still discussed [1-3]. However, a study of reverse current in quasi-vertical GaN-on-Si p-i-n diodes has revealed that the density of electrically active defects causing an excess leakage current (ELC, i.e. outlier of current distribution) is only about  $5 \times 10^3 \text{ cm}^{-2}$  [4]. Low-frequency noise spectroscopy, particularly random telegraph noise (RTN), is useful for characterizing intrinsic or stress-induced defects in GaN devices [5-8]. In this work, we investigate RTN and ELC in GaN-on-Si p-i-n diodes and relate them to the presence of active intrinsic defects.

The p-i-n diode is a fundamental part of every gate stack of a normally-off HEMT. Here, an AlGaIn barrier (15nm) and und-GaN (420nm) layer are placed in between the top p-GaN and 1 $\mu\text{m}$  thick n-AlGaIn at the bottom [4]. Devices with a diameter of 10-75 $\mu\text{m}$  have a boron-implanted sidewall to reduce the perimeter leakage.

Two or multi-level RTN, with amplitude  $\Delta I$  in pA - nA range, is observed at both bias polarizations, mostly in devices having an ELC at reverse bias. The bias dependence of  $\Delta I$  in both polarizations follows the IV characteristics of the ELC component, attributing thus RTN to fluctuations in ELC. The large relative RTN amplitude,  $\Delta I/I$ , up to 30% indicates that ELC flows through a constriction related to an extended defect, e.g. closed-core dislocation [4]. Defect- and/or electric field-assisted processes are the origin of ELC. The bias dependence of RTN mean pulse widths (10ms to 10s range) suggests that RTN is due to capture/emission or structural reconfiguration processes on a single point defect which takes part of the extended defect. The work was supported by ALL2GaN EU project no. 101111890.

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